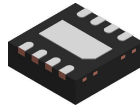


**DATA BOOK
PACKAGE OUTLINE**

DRAFTER:	ANIS FAUZI	DATE:	08/21/2021			DIMENSIONS IN MILLIMETERS		
DESIGNER:		DATE:		 TEXAS INSTRUMENTS SEMICONDUCTOR OPERATIONS CODE IDENTITY NUMBER 01295 ePOD, NGR0008C / WSON, 8 PIN, 0.5 MM PITCH				
CHECKER:	K. SINCERBOX	DATE:	03/15/2022					
ENGINEER:	B. CARLISLE	DATE:	03/15/2022					
APPROVED:	D. CHIN & D. MILO	DATE:	03/15/2022					
RELEASED:	K. SINCERBOX	DATE:	03/15/2022					
TEMPLATE INFO:		DATE:		SCALE	SIZE	4227008	REV	PAGE
	EDGE# 4218519		04/07/2016	NTS	A		D	1 OF 5

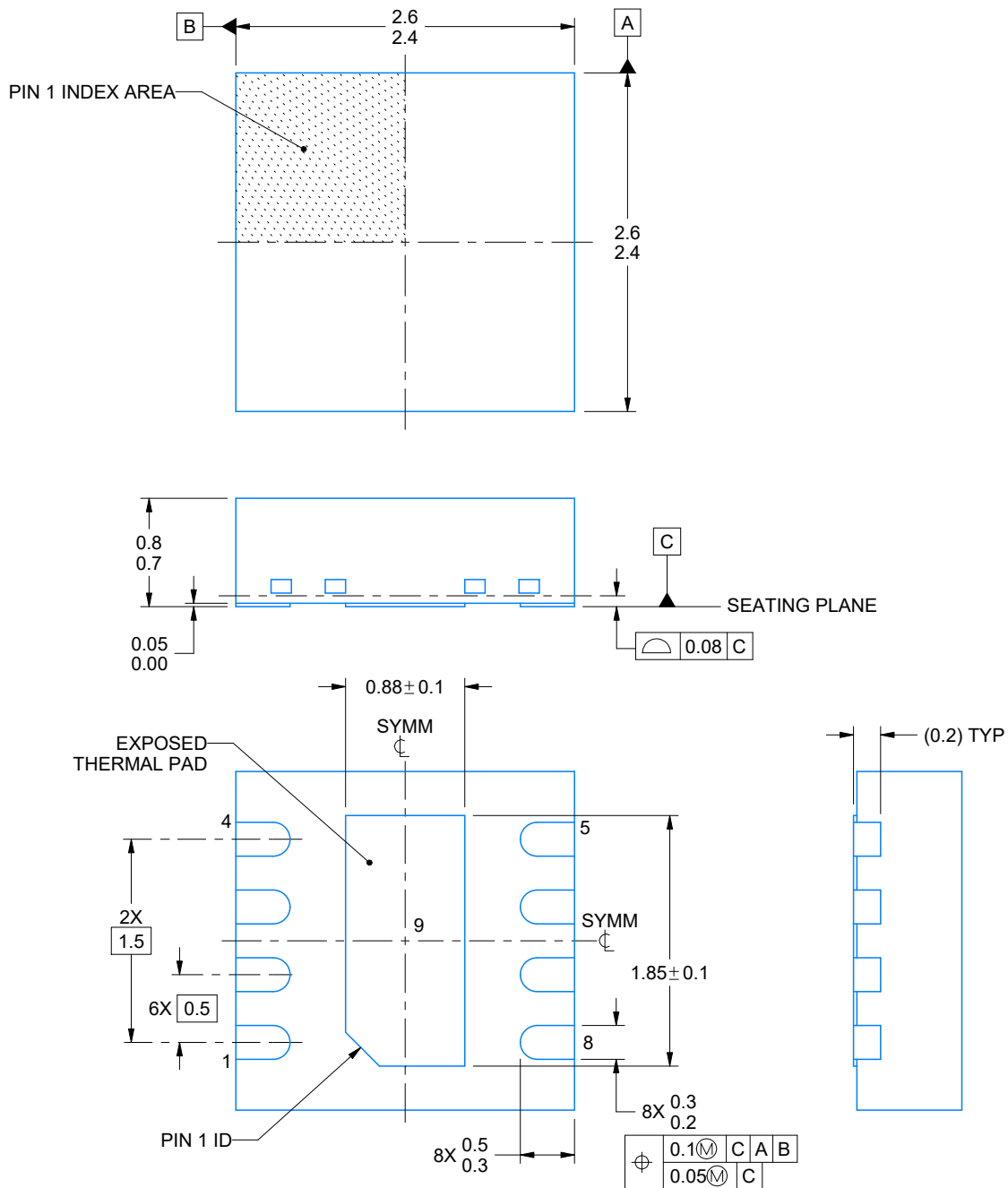
NGR0008C



PACKAGE OUTLINE

WSO - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



4227008/D 03/2022

NOTES:

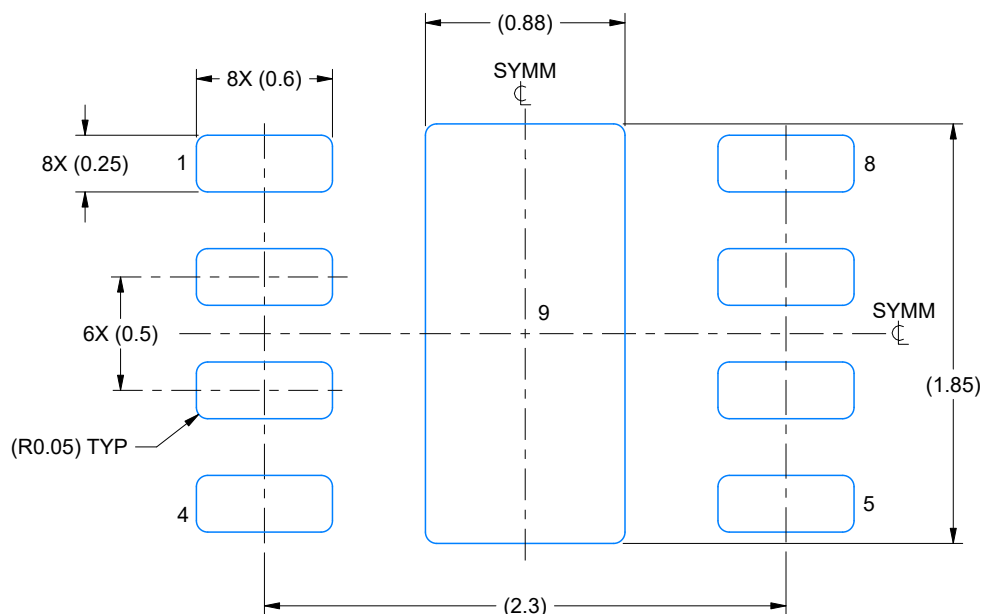
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

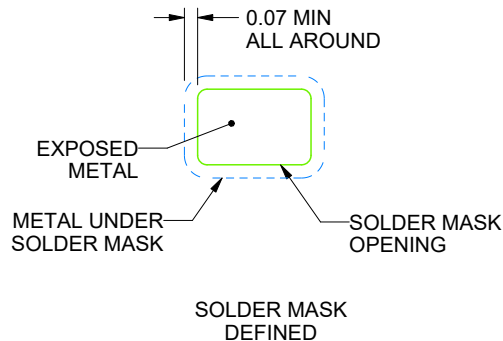
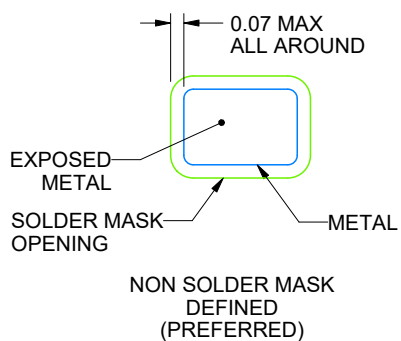
NGR0008C

WSN - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:30X



SOLDER MASK DETAILS

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NOTES: (continued)

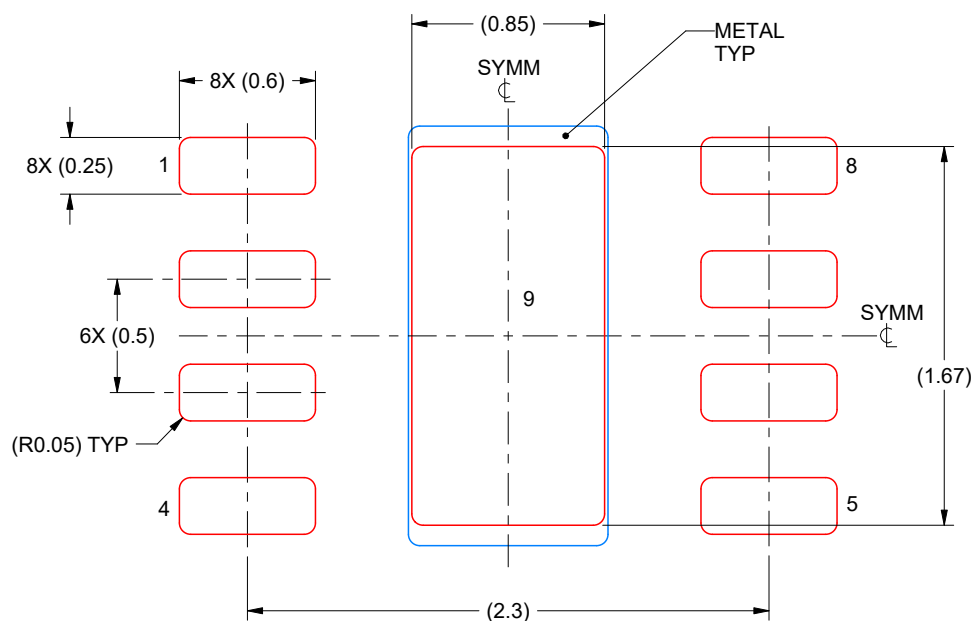
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slue271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

NGR0008C

WSN - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 9:
87% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:30X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2196131	08/21/2021	M. MONZINGO / ANIS FAUZI
B	1.85± 0.1 WAS 1.5± 0.1; (1.85) WAS (1.5); (1.67) WAS (1.38);	2196674	09/07/2021	M. MONZINGO / K. SINCERBOX
C	SIDE WALL METAL THICKNESS (0.2) TYP WAS (0.1) TYP	2197594	11/12/2021	M. MONZINGO / K. SINCERBOX
D	CORRECT THERMAL PAD NUMBERING	2199132	2022	B. CARLISLE / K. SINCERBOX